FORM PTO-1595 (Modified) (Rev. 6-93) OMB No. 0651-0011 (exp.494) Copyright 1994-97 LegalSt

Name of Person Signing

09-18-2001

Docket No.: HCD-211

U.S. DEPARTMENT OF COMMERCE

Patent and Trademark Office P08/REV02 Tab settings -To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof. 1. Name of conveying party(ies): 2. Name and address of receiving party(ies): Che-Yu Li David A. Lysack Name: HIGH CONNECTION DENSITY, INC. Brian D. Harry John J. Kresse Internal Address: Additional names(s) of conveying party(ies) ☐ Yes 🛛 No 3. Nature of conveyance: Street Address: 1267 Borregas Avenue ★ Assignment Merger ☐ Security Agreement Change of Name City: Sunnyvale _____ State: CA ZIP: 94089 ☐ Other Execution Date: 8/31/01; 9/4/01 4. Application number(s) or registration numbers(s): If this document is being filed together with a new application, the execution date of the application is: A. Patent Application No.(s) B. Patent No.(s) 09/932,525 Additional numbers attached?

Yes

No 5. Name and address of party to whom correspondence 6. Total number of applications and patents involved: concerning document should be mailed: 7. Total fee (37 CFR 3.41):....\$ 40.00 Name: Mark Levy ☐ Enclosed - Any excess or insufficiency should be Internal Address: SALZMAN & LEVY, Ste. 902 credited or debited to deposit account Authorized to be charged to deposit account Street Address: 19 Chenango St. 8. Deposit account number: 19-0077 ZIP: 13901 State: NY City: Binghamton DO NOT USE THIS SPACE 99/17/2001 LINUELLER 00000168 190077 09938585 01 FC:581 40.00 CH To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy 9. Statement and signature. 0 of the original document. Mark Levy Date Signature

Total number of pages including cover sheet, attachments, and documen

REEL: 012158 FRAME: 0352

Assignment of Rights, Title and Interest in Invention (Multiple inventors; single assignee)			Docket No. HCD-211	
his is an As	ssignment of the following rig.	hts, title and interest: (check all that apply):		
×	United States of America rights, title and interest in the invention			
×	Foreign rights, title and interest in the invention			
×	United States Patent Application Serial No. 09/932,525			
	Date of Execution: 8/16/01 Date of Filing: 8/17/01			
	United States Provisional Patent Application Serial No.			
	United States Patent No(s).			
	International (PCT) Patent Application Serial No.			
	Other (specify)			
Title of the I	Invention			
I/O STACKE	ED MODULES FOR INTEGRA	IED CIRCUITS		
	Name	Address		
Che-Yu Li		112 Juniper Drive, Ithaca, New York 1485	0	
David A. Lysack		8411 Sugar Pine Circle, Liverpool, New Yo	ork 13090	
Brian D. Harry		37 Braeside Road, Baldwinsville, New Yor	rk 13027	
John J. Kresse		2 Goosberry Lane, Liverpool, New York 13	3090	
Assignee				
	Name	Address		
High Con	nection Density, Inc.	1267 Borregas Avenue Sunnyvale, CA 94089-1308		
<u> </u>		[Page 1 of 2]	AS03A/REV01	

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Assignment of Rights, Title and Interest in Invention (Multiple inventors; single assignee)

Docket No. HCD-211

Whereas, we, the above-identified Inventors, have invented certain new and useful improvements in the Invention identified above and described in the above-identified patent application(s) and/or patent(s) (hereinafter referred to as "Invention");

And, whereas we desire to assign our above-identified rights, title and interest in the Invention to the above-identified Assignee;

Now, this indenture witnesseth, that for good and valuable consideration, the receipt whereof is hereby acknowledged:

We hereby assign, sell and transfer our above-identified rights, title and interest in said Invention, said application(s) as identified above, including any divisions, continuations, and continuations-in-part thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted or have granted for said Invention, and in and to any and all reissues and reexaminations thereof, and in and to any and all priority rights, Convention rights, and other benefits accruing or to accrue to us with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, unto said Assignee;

And we hereby authorize and request the Commissioner of Patents and Trademarks to issue any United States Letters Patent which may issue for said Invention to said Assignee, as assignee of the whole right, title and interest thereto;

And we further agree to sign and execute all necessary and lawful future documents, including applications for foreign patents, for filing divisions, continuations and continuations-in-part of said application for patent, and/or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesuid Invention, as the Assignee or its Designee(s) may from time to time require and prepare at its own expense.

Inventors' Signatures (if Noturization is desired, do not sign here and proceed to next page)

Name	Signature/Date
Che-Yu Li	8/31(0)
David A. Lysack	Daniel 9/4/01
Brian D. Harry	Brian 1 April 9/4/01
John J. Kresse	Jan 1. Luca / 9.4-01

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